

BF 1608 Series

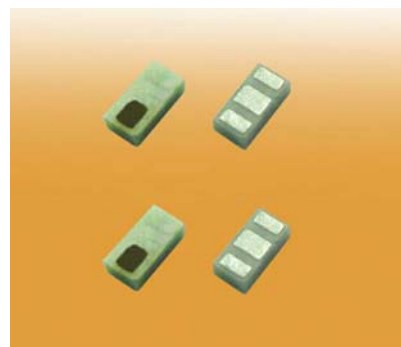
Multilayer Chip Band-Pass Filters

Features

- ❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.
- ❖ HF & RoHS Compliant

Applications

- ❖ WiFi communication systems.



Specifications

Part Number	Frequency Range (MHz)	Insertion Loss @ BW (dB)	Return Loss @ BW(dB)	Frequency (MHz)	Attenuation (dB)
BF1608-N5R5NAH_	5150~5950	0.7 max.@25°C 0.95 max.@-40~105°C	12 min.	700 ~ 2690	35 min.
				3400 ~ 3800	30 min.
				7250 ~ 7800	12 min.
				10300 ~ 11700	20 min.
				15450 ~ 17850	4 typ.

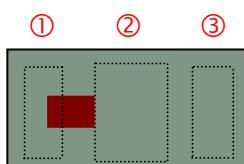
Q'ty/Reel (pcs) : 4,000
 Operating Temperature Range : -40 ~ +105 °C
 Storage Temperature Range : -40 ~ +105 °C
 Storage Period : 12 months max.
 Power Capacity : 3W max.

Part Number

BF 1608 - N 5R5 NAH □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	BF : Band-Pass Filter	② Dimensions (L × W)	1.6 × 0.8 mm
③ Material Code	N	④ Frequency Range	5R5=5500MHz
⑤ Specification Code	NAH	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

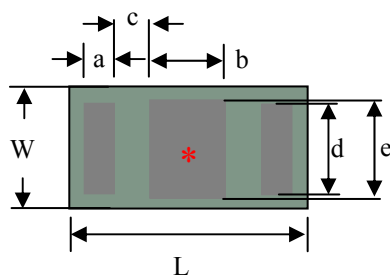
Terminal Configuration



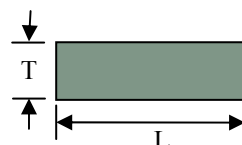
No.	Terminal Name	No.	Terminal Name
①	IN	③	OUT
②	GND		

Dimensions and Recommended PC Board Pattern

Unit: mm



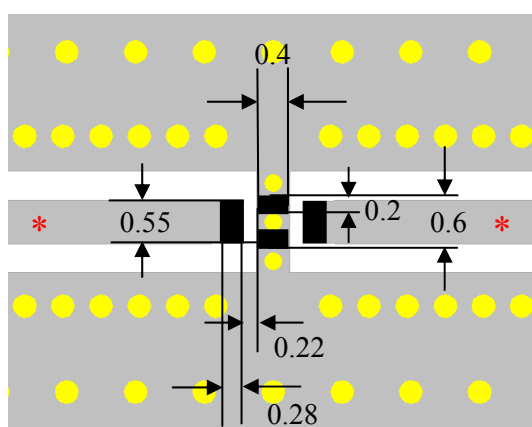
< Bottom View >



< Side View >

***Electrode material: Ni/Sn**

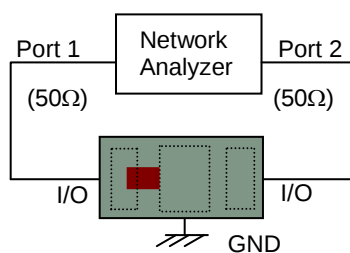
Mark	L	W	T	a	b	c	d	e
Dimensions	1.6 ± 0.15	0.8 ± 0.15	0.6 max.	0.25 ± 0.1	0.4 ± 0.1	0.23 ± 0.05	0.55 ± 0.10	0.60 ± 0.10



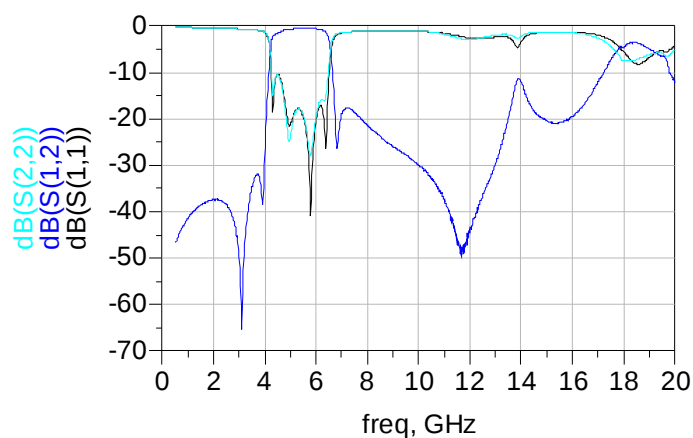
-  Solder Resist
-  Land
-  Through-hole (φ 0.3, 0.23)

* Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram



Electrical Characteristics (T=25oC)

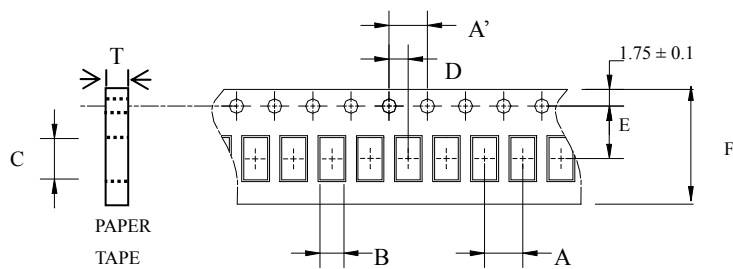


Notes

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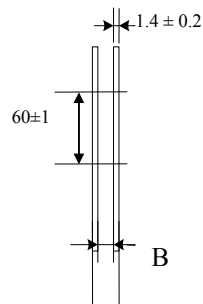
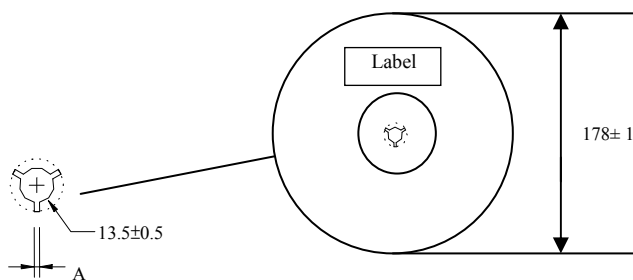
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1608	4.0±0.1	4.0±0.1	1.10±0.1	1.92±0.1	2.0±0.1	3.5±0.1	8.0±0.1	0.75±0.05	4,000pcs	Paper

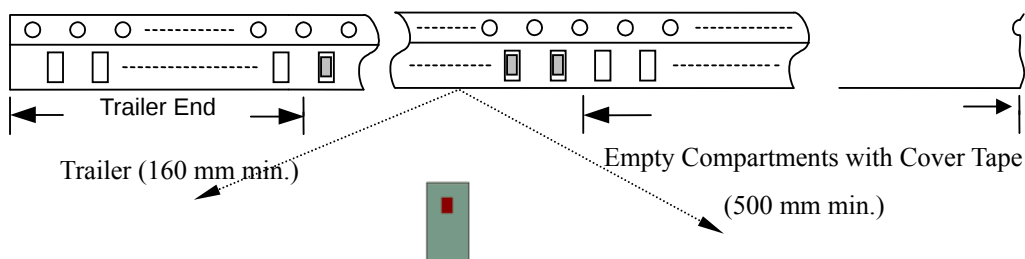
❖Reel Dimensions (Unit: mm)



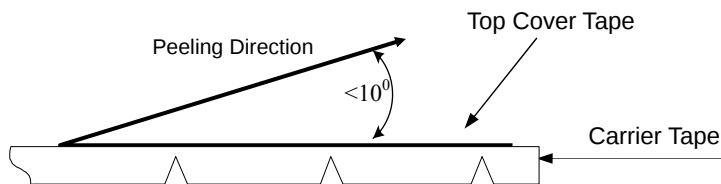
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
1608	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape



❖Peel-off Force



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

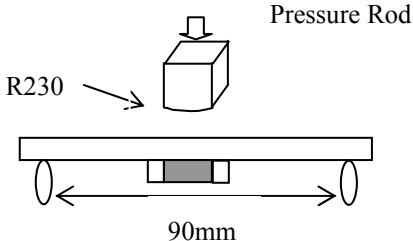
❖Storage Conditions

- (1) Temperature: $5 \sim 35^{\circ}\text{C}$, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

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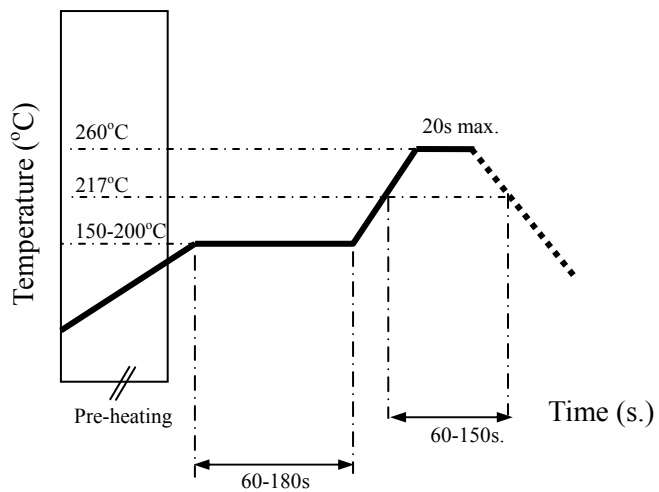
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	1. No apparent damage 2. More than 95% of the terminal electrode shall be covered with new solder	1. Preheat: $120 \pm 5^{\circ}\text{C}$ 2. Solder: $245 \pm 5^{\circ}\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	1. 10N minimum	1. Solder specimen onto test jig. 2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	1. No apparent damage	1. Solder specimen onto test jig (FR4, 1.6mm) using the recommend soldering profile. 2. Apply a bending force of 2mm deflection. (Chip length<4.5mm) 
Heat/Humidity Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $85 \pm 2^{\circ}\text{C}$ 2. Humidity: 90% ~ 95% RH 3. Duration: 1000 ± 48hrs 4. Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	1. No apparent damage 2. Fulfill the electrical specification after test	1. One cycle/step 1 : $125 \pm 5^{\circ}\text{C}$ for 30 min step 2 : $-40 \pm 5^{\circ}\text{C}$ for 30 min 2. No of cycles : 100 3. Recovery:1-2 hrs
Low Temperature Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $-40 \pm 5^{\circ}\text{C}$ 2. Duration: 500 ± 24hrs 3. Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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